

## **PACKAGE STRUCTURE AND MANUFACTURING METHOD THEREOF**

### **ABSTRACT OF THE DISCLOSURE**

A package structure includes a circuit substrate, a light emitting diode array, a first encapsulant, and a sealant. The circuit substrate includes a top surface and a side surface of the circuit substrate. The light emitting diode array is disposed on the top surface of the circuit substrate. The first encapsulant is disposed above the circuit substrate. The first encapsulant includes a main portion and an extension portion, in which the main portion of the first encapsulant is disposed parallel to the top surface of the circuit substrate, and the extension portion of the first encapsulant extends to the side surface of the circuit substrate. The sealant is disposed below the extension portion of the first encapsulant, and the sealant contacts the first encapsulant and the circuit substrate. The first encapsulant and the sealant together form a coplanar surface.

Fig. 2H